NTC thermistors for inrush current limiting

Leaded and coated disks

Series/Type: **B57236S0***M0****

Date: December 2011

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Applications

- Switch-mode power supplies

Features

- Useable in series connections up to 265 V_{RMS}
- Coated thermistor disk
- Kinked leads of tinned copper wire
- Wide resistance range
- UL approval (E69802)

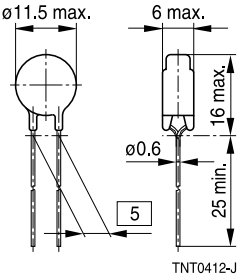
Options

Resistance tolerance <20% and alternative lead configurations available on request

Delivery mode

Bulk (standard) or with cardboard tape on 350-mm reel

Dimensional drawing



Dimensions in mm
Approx. weight 1 g

General technical data

Climatic category	(IEC 60068-1)		55/170/21	
Max. power	(at 25 °C)	P_{max}	2.1	W
Resistance tolerance		$\Delta R_R/R_R$	±20	%
Rated temperature		T_R	25	°C
Dissipation factor	(in air)	δ_{th}	approx. 10	mW/K
Thermal cooling time constant	(in air)	τ_c	approx. 70	s
Heat capacity		C_{th}	approx. 700	mJ/K

Electrical specification and ordering codes

R_{25} Ω	I_{max} (0...65 °C) A	$B_{25/100}$ K	C_{test}[1] 230 V AC µF	C_{test}[1] 110 V AC µF	Param. for R(I)[1] k	Param. for R(I)[1] n	Ordering code
2.2	6.0	2700	200	800	0.806	−1.30	B57236S0229M0**
2.5	5.5	2700	200	800	0.621	−1.27	B57236S0259M0**
3	5.0	2700	300	1200	0.804	−1.34	B57236S0309M0**
4.7	4.6	2800	300	1200	0.740	−1.30	B57236S0479M0**
5	4.5	2800	300	1200	0.761	−1.30	B57236S0509M0**
8	3.7	2900	300	1200	1.11	−1.34	B57236S0809M0**
10	3.5	2900	300	1200	0.942	−1.32	B57236S0100M0**
12	3.2	2900	300	1200	1.00	−1.32	B57236S0120M0**
16	2.9	2965	300	1200	1.08	−1.33	B57236S0160M0**
20	2.8	3065	300	1200	1.13	−1.34	B57236S0200M0**
25	2.5	3065	300	1200	1.22	−1.34	B57236S0250M0**

** = Delivery mode
00 = Bulk
51 = Reel packing

1) For details on the capacitance C_{test} as well as on the parameters k and n refer to "Application notes", chapters 1.6 and 1.7.

R_{25} Ω	I_{max} (0...65 °C) A	$B_{25/100}$ K	C_{test} [1] 230 V AC µF	C_{test} [1] 110 V AC µF	Param. for R(I)[1] k	Param. for R(I)[1] n	Ordering code
50	1.9	3165	300	1200	1.44	−1.38	B57236S0500M0**
80	1.6	3300	400	1600	1.64	−1.37	B57236S0800M0**
120	1.5	3450	400	1600	1.74	−1.39	B57236S0121M0**

** = Delivery mode
00 = Bulk
51 = Reel packing

Reliability data

Test	Standard	Test conditions	$\Delta R_{25}/R_{25}$ (typical)	Remarks
Storage in dry heat	IEC 60068-2-2	Storage at upper category temperature T: 170 °C t: 1000 h	< 10%	No visible damage
Storage in damp heat, steady state	IEC 60068-2-78	Temperature of air: 40 °C Relative humidity of air: 93% Duration: 21 days	< 5%	No visible damage
Rapid temperature cycling	IEC 60068-2-14	Lower test temperature: −55 °C Upper test temperature: 170 °C Number of cycles: 10	< 10%	No visible damage
Endurance		$I = I_{max}$ t: 1000 h	< 10%	No visible damage
Cyclic endurance		$I = I_{max}$, 1000 cycles On-time = 1 min Cooling time = 6 min	< 10%	No visible damage
Transient load		Capacitance = C_{test} Number of cycles: 1000	< 5%	No visible damage

Note

- The self-heating of a thermistor during operation depends on the load applied and the applicable dissipation factor.
- When loaded with maximum allowable current/power and the specified dissipation factor is taken as a basis, the NTC thermistor may reach a mean temperature of up to 250 °C.
- The heat developed during operation will also be dissipated through the lead wires. So the contact areas, too, may become quite hot at maximum load.
- When mounting NTC thermistors you have to ensure that there is an adequate distance between the thermistor and all parts which are sensitive to heat or combustible.

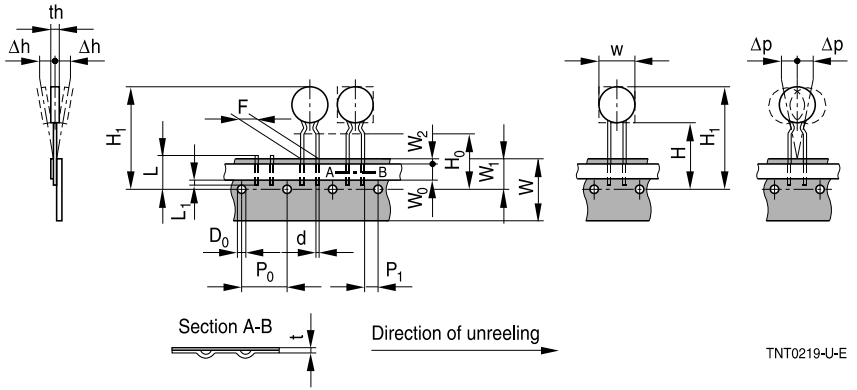
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Taping and packing

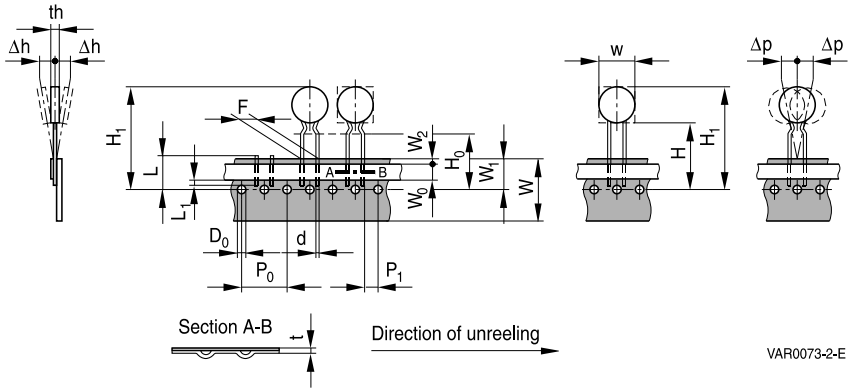
1 Taping of radial leaded ICL NTC thermistors according to the specified lead spacing

Dimensions and tolerances

Lead spacing F = 5.0 mm (taping to IEC 60286-2)



Lead spacing F = 7.5 mm (taping based on IEC 60286-2)

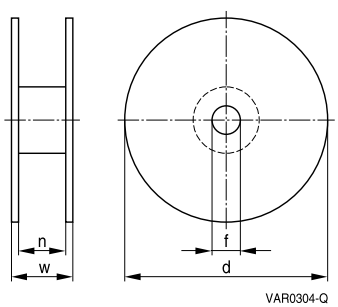


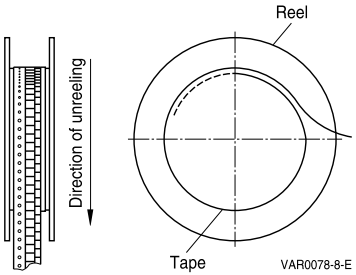
Dimensions (mm)

	Lead spacing 5 mm	Tolerance of lead spacing 5 mm	Lead spacing 7.5 mm	Tolerance of lead spacing 7.5 mm	Remarks
w	≤12.0	max.	≥12.0	max.	please refer to dimensional drawings
th	6.0	max.	7	max.	please refer to dimensional drawings
d	0.5/0.6	±0.05	0.8/1.0	±0.05	please refer to dimensional drawings
P_0	12.7	±0.3	12.7	±0.3	±1 mm / 20 sprocket holes
P_1	3.85	±0.7	8.95	±0.8	
F	5.0	+0.6/−0.1	7.5	±0.8	
Δh	0	±2.0	0	Depends on th	measured at top of component body
Δp	0	±1.3	0	±2.0	
W	18.0	±0.5	18.0	±0.5	
W_0	5.5	min.	11.0	min.	peel-off force ≥5 N
W_1	9.0	+0.75/−0.5	9.0	+0.75/−0.5	
W_2	3.0	max.	3.0	max.	
H	18.0	+2.0/−0	18.0	+2.0/−0	
H_0	16.0	±0.5	16.0	±0.5	
H_1	32.2	max.	45.0	max.	
D_0	4.0	±0.2	4.0	±0.2	
t	0.9	max.	0.9	max.	without wires
L	11.0	max.	11.0	max.	
L_1	4.0	max.	4.0	max.	

Types of packing

Reel packing





Reel dimensions (in mm)

Reel type	d	f	n	w
I	360 max.	31 ±1	approx. 45	54 max.
II	500 max.	23 ±1	approx. 59	72 max.

Bulk packing

The components are packed in cardboard boxes, the size of which depends on the order quantity.

Mounting instructions

1 Soldering

1.1 Leaded NTC thermistors

Leaded thermistors comply with the solderability requirements specified by CECC.

When soldering, care must be taken that the NTC thermistors are not damaged by excessive heat. The following maximum temperatures, maximum time spans and minimum distances have to be observed:

	Dip soldering	*Iron soldering*
Bath temperature	max. 260 °C	max. 360 °C
Soldering time	max. 4 s	max. 2 s
Distance from thermistor	min. 6 mm	min. 6 mm

Under more severe soldering conditions the resistance may change.

Solderability (test to IEC 60068-2-20)
Preconditioning: Immersion into flux F-SW 32.
Evaluation criterion: Wetting of soldering areas ≥95%.

Solder	Bath temperature (°C)	Dwell time (s)
SnAg (3.0 ... 4.0), Cu (0.5 ... 0.9)	245 ±3	3

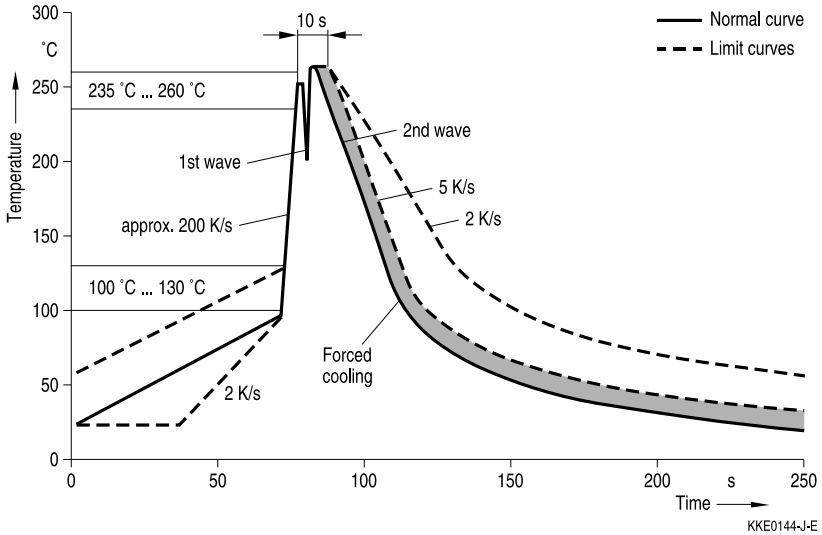
1.1.1 Resistance to soldering heat (test to IEC 60068-2-20)

Preconditioning: Immersion into flux F-SW 32.

Solder	Bath temperature (°C)	Dwell time (s)
SnAg (3.0 ... 4.0), Cu (0.5 ... 0.9)	260 −5	10

Wave soldering

Temperature characteristic at component terminal with dual wave soldering



2 Robustness of terminations

The leads meet the requirements of IEC 60068-2-21. They may not be bent closer than 4 mm from the solder joint on the thermistor body or from the point at which they leave the feed-throughs. During bending, any mechanical stress at the outlet of the leads must be removed. The bending radius should be at least 0.75 mm.

Tensile strength: Test Ua1:

Leads	0.50 < ∅ ≤0.80 mm =	10.0 N
	0.80 < ∅ ≤1.25 mm =	20.0 N

Bending strength: Test Ub:

Two 90°-bends in opposite directions at a weight of 0.25 kg.

Torsional strength: Test Uc: severity 2

The lead is bent by 90° at a distance of 6 to 6.5 mm from the thermistor body.

The bending radius of the leads should be approx. 0.75 mm. Two torsions of 180° each (severity 2).

When subjecting leads to mechanical stress, the following should be observed:

Tensile stress on leads

During mounting and operation tensile forces on the leads are to be avoided.

Bending of leads

Bending of the leads directly on the thermistor body is not permissible.

A lead may be bent at a minimum distance of twice the wire's diameter +2 mm from the solder joint on the thermistor body. During bending the wire must be mechanically relieved at its outlet. The bending radius should be at least 0.75 mm.

Twisting of leads

The twisting (torsion) by 180° of a lead bent by 90° is permissible at 6 mm from the bottom of the thermistor body.

3 Sealing and potting

When thermistors are sealed, potted or overmolded, there must be no mechanical stress caused by thermal expansion during the production process (curing / overmolding process) and during later operation. The upper category temperature of the thermistor must not be exceeded. Ensure that the materials used (sealing / potting compound and plastic material) are chemically neutral.

4 Cleaning

If cleaning is necessary, mild cleaning agents such as ethyl alcohol and cleaning gasoline are recommended. Cleaning agents based on water are not allowed. Ultrasonic cleaning methods are permissible.

5 Storage

In order to maintain their solderability, thermistors must be stored in a non-corrosive atmosphere. Humidity, temperature and container materials are critical factors.

The components should be left in the original packing. Touching the metallization of unsoldered thermistors may change their soldering properties.

Storage temperature: −25 °C up to 45 °C

Max. relative humidity (without condensation):

<95%, maximum 30 days per annum

Solder the thermistors listed in this data book after shipment from EPCOS within the time specified:

Leaded components: 24 months

Cautions and warnings

General

See "Important notes" at the end of this document.

Storage

- Store thermistors only in original packaging. Do not open the package before storage.
- Storage conditions in original packaging: storage temperature −25 °C ... +45 °C, relative humidity ≤75% annual mean, maximum 95%, dew precipitation is inadmissible.
- Avoid contamination of thermistors surface during storage, handling and processing.
- Avoid storage of thermistor in harmful environments like corrosive gases (SO_x, Cl etc).
- Solder thermistors after shipment from EPCOS within the time specified:
  − Leaded components: 24 months

Handling

- NTC thermistors must not be dropped. Chip-offs must not be caused during handling of NTCs.
- Components must not be touched with bare hands. Gloves are recommended.
- Avoid contamination of thermistor surface during handling.
- In case of exposure of the NTC thermistors to water, electrolytes or other aggressive media, these media can penetrate the coating and reach the surface of the ceramic. Low-ohmic or high-ohmic behavior may occur due to the formation of an electrolyte with metals (silver/lead/tin from metallization or solder). Low-ohmic behavior is caused by electrochemical migration, high-ohmic behavior by dissolving of the electrode. Ineither case, the functionality of the NTC thermistors can not be assured.

Bending / twisting leads

- A lead (wire) may be bent at a minimum distance of twice the wire's diameter plus 4 mm from the component head or housing. When bending ensure the wire is mechanically relieved at the component head or housing. The bending radius should be at least 0.75 mm.
- Twisting (torsion) by 180° of a lead bent by 90° is permissible at 6 mm from the bottom of the thermistor body.

Soldering

- Use resin-type flux or non-activated flux.
- Insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended.
- Complete removal of flux is recommended.

Mounting

- When NTC thermistors are encapsulated with sealing material or overmolded with plastic material, the precautions given in chapter “Mounting instructions”, “Sealing and potting” must be observed.
- Electrode must not be scratched before/during/after the mounting process.
- Contacts and housings used for assembly with thermistor have to be clean before mounting.
- During operation, the inrush current limiters surface temperature can be very high. Ensure that adjacent components are placed at a sufficient distance from the thermistor to allow for proper cooling of the thermistors.
- Ensure that adjacent materials are designed for operation at temperatures comparable to the surface temperature of the thermistor. Be sure that surrounding parts and materials can withstand this temperature.
- Make sure that inrush current limiters are adequately ventilated to avoid overheating.
- Avoid contamination of thermistor surface during processing.

Operation

- Use thermistors only within the specified operating temperature range.
- Use inrush current limiters only within the specified voltage and current ranges.
- Environmental conditions must not harm the thermistors. Use thermistors only in normal atmospheric conditions.
- Contact of NTC thermistors with any liquids and solvents should be prevented. It must be ensured that no water enters the NTC thermistor (e.g. through plug terminals). For measurement purposes (checking the specified resistance vs. temperature), the component must not be immersed in water but in suitable liquids (e.g. Galden).
- In case of exposure of the NTC thermistors to water, electrolytes or other aggressive media, these media can penetrate the coating and reach the surface of the ceramic. Low-ohmic or high-ohmic behavior may occur due to the formation of an electrolyte with metals (silver/lead/tin from metallization or solder). Low-ohmic behavior is caused by electrochemical migration, high-ohmic behavior by dissolving of the electrode. Ineither case, the functionality of the NTC thermistorscannot be assured.
- Be sure to provide an appropriate fail-safe function to prevent secondary product damage caused by malfunction (e.g. use a metal oxide varistor for limitation of overvoltage condition).

Symbols and terms

Symbol	English	German
C_{test}	Test capacitance	Prüfkapazität (elektrisch)
C_{th}	Heat capacitance	Wärmekapazität
I	Current	Strom
I_{max}	Maximum current within stated temperature range	Maximalstrom im angegebenen Temperaturbereich
I_{NTC}	NTC current	Heißleiter-Strom
I_R	Rated current	Nennstrom
P_{25}	Maximum power at 25 °C	Maximale Leistung bei 25 °C
P_{diss}	Power dissipation	Verlustleistung
P_{el}	Electrical power	Elektrische Leistung
P_{max}	Maximum power within stated temperature range	Maximale Leistung im angegebenenTemperaturbereich
R_R	Rated resistance	Nennwiderstand
$\Delta R_R/R_R$	Resistance tolerance	Widerstandstoleranz
R_T	Resistance at temperature T (e.g. R_{25} = resistance at 25 °C)	Widerstand bei Temperatur T (z.B. R_{25} = Widerstand bei 25 °C)
T	Temperature	Temperatur
t	Time	Zeit
T_A	Ambient temperature	Umgebungstemperatur
t_a	Thermal threshold time	Thermische Ansprechzeit
T_{max}	Upper category temperature	Obere Grenztemperatur (Kategorietemperatur)
T_{min}	Lower category temperature	Untere Grenztemperatur (Kategorietemperatur)
T_R	Rated temperature	Nenntemperatur
V	Voltage	Spannung
V_{load}	Load voltage	Ladespannung
V_{NTC}	Voltage drop across an NTC thermistor	Spannungsabfall am Heißleiter
α	Temperature coefficient	Temperaturkoeffizient
Δ	Tolerance, change	Toleranz, Änderung
δ_{th}	Dissipation factor	Wärmeleitwert
τ_c	Thermal cooling time constant	Thermische Abkühlzeitkonstante

Abbreviations / Notes

Symbol	English	German
*	To be replaced by a number in ordering codes, type designations etc.	Platzhalter für Zahl im Bestellnummern-code oder für die Typenbezeichnung.
+	To be replaced by a letter.	Platzhalter für einen Buchstaben.
	All dimensions are given in mm.	Alle Maße sind in mm angegeben.
	The commas used in numerical values denote decimal points.	Verwendete Kommas in Zahlenwerten bezeichnen Dezimalpunkte.

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